

RELIABILITY REPORT
FOR
MAX1554ETA
PLASTIC ENCAPSULATED DEVICES

September 5, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by



Jim Pedicord
Quality Assurance
Manager, Reliability Operations

Reviewed by



Bryan J. Preeshl
Quality Assurance
Executive Director of QA

Conclusion

The MAX1554 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX1554 drives white LEDs in series with a constant current to provide efficient display backlighting in cellular phones, PDAs, and other hand-held devices. The step-up converter includes an internal 40V, low RDSON, N-channel MOSFET switch for high efficiency and maximum battery life. The MAX1554 has a 970mA current limit for driving up to ten white LEDs

A single analog/PWM Dual Mode™ input provides two simple means of brightness adjustment. A separate enable input provides on/off control. Soft-start minimizes inrush current during startup.

B. Absolute Maximum Ratings

<u>Item</u>	<u>Rating</u>
VCC, FB, OV to GND	-0.3V to +6.0V
LX to GND	-0.3V to +45V
EN, BRT, SS to GND	-0.3V to (VCC + 0.3V)
ILX	0.9ARMS
Operating Temperature Range	-40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Continuous Power Dissipation (TA = +70C)	
8-PIN TDFN (3mm x 3mm)	1951mW
Derates above +70°C	
8-PIN TDFN (3mm x 3mm)	24.4mW/°C

II. Manufacturing Information

A. Description/Function:	High-Efficiency, 40V Step-Up Converter for 2 to 10 White LEDs
B. Process:	BCD80
C. Number of Device Transistors:	740
D. Fabrication Location:	Oregon, USA
E. Assembly Location:	Thailand
F. Date of Initial Production:	October, 2001

III. Packaging Information

A. Package Type:	8-Pin TDFN (3mm x 3mm)
B. Lead Frame:	Copper
C. Lead Finish:	Solder Plate
D. Die Attach:	Silver-Filled Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	# 05-9000-0580
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-112:	Level 1

IV. Die Information

A. Dimensions:	92 X 61 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	3 microns (as drawn)
F. Minimum Metal Spacing:	3 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Jim Pedicord (Manager, Reliability Operations)
Bryan Preeshl (Executive Director of QA)
Kenneth Huening (Vice President)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4389 \times 47 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

 Temperature Acceleration factor assuming an activation energy of 0.8eV

$$\lambda = 23.10 \times 10^{-9}$$

$$\lambda = 23.10 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on any lot that exceeds this reliability control level. Attached Burn-In Schematic (Spec. # 06-6153) shows the static Burn-In circuit. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

C. E.S.D. and Latch-Up Testing

The PN19-1 die type has been found to have all pins able to withstand a transient pulse of $\pm 1000\text{V}$, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of $\pm 250\text{mA}$.

Table 1
Reliability Evaluation Test Results

MAX1554ETA

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		47	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	DFN	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.

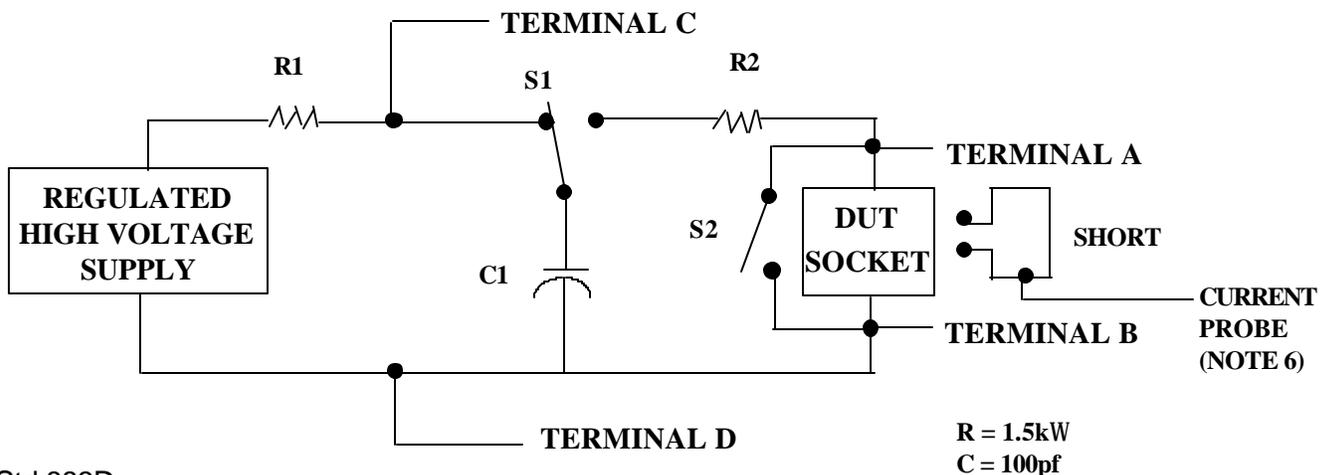
2/ No connects are not to be tested.

3/ Repeat pin combination 1 for each named Power supply and for ground

(e.g., where V_{PS1} is V_{DD} , V_{CC} , V_{SS} , V_{BB} , GND, $+V_S$, $-V_S$, V_{REF} , etc).

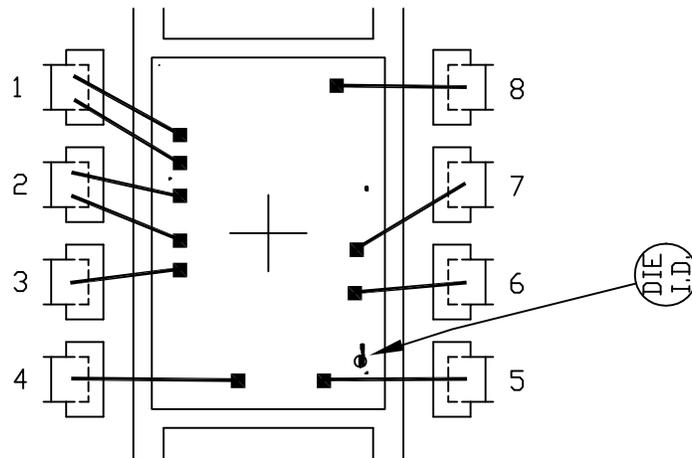
3.4 Pin combinations to be tested.

- a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1} , or V_{SS2} or V_{SS3} or V_{CC1} , or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.

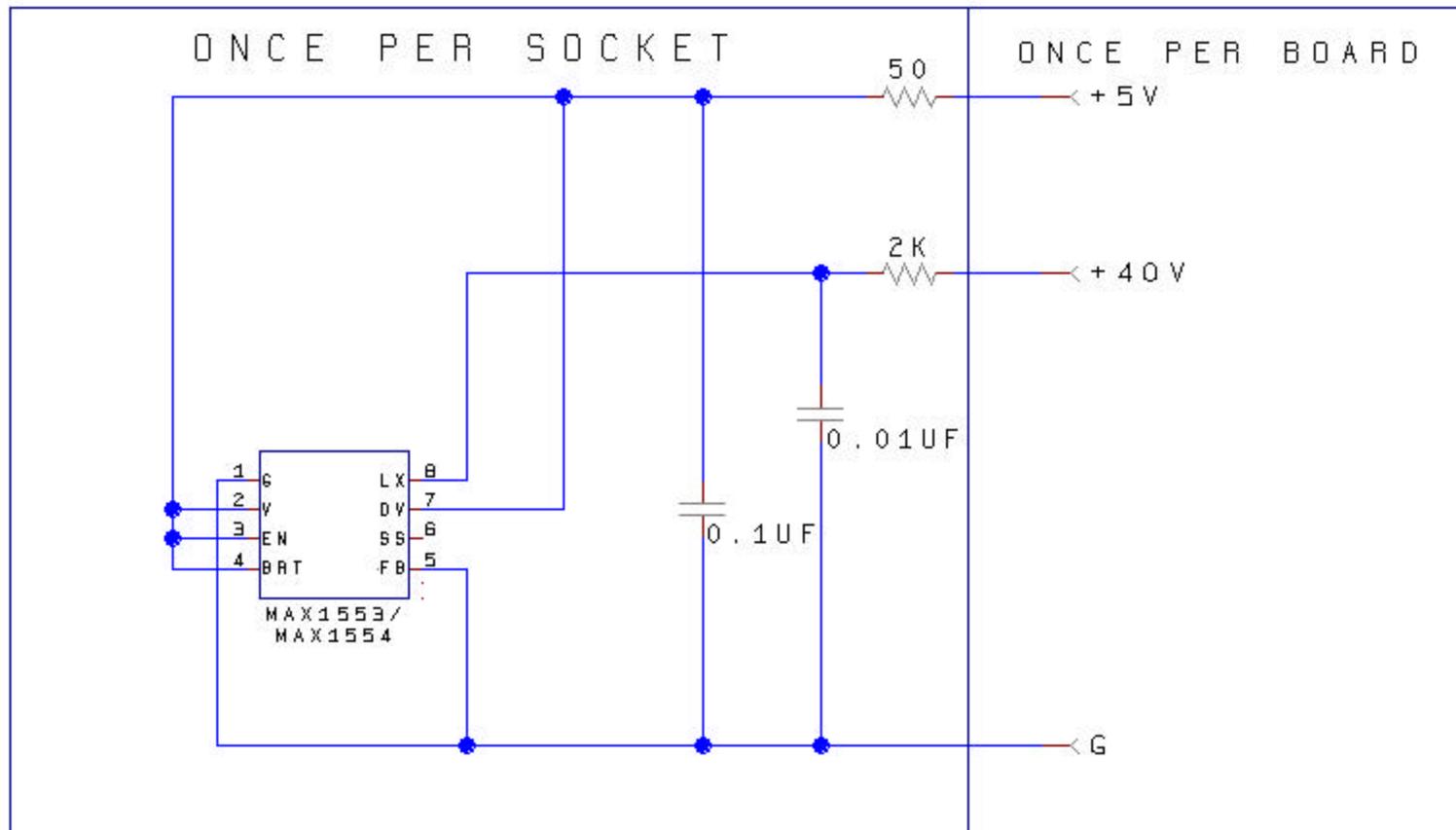


3x3x0.8 MM QFN THIN PKG.

EXPOSED PAD PKG.



PKG. CODE: T833-1		SIGNATURES	DATE	 CONFIDENTIAL & PROPRIETARY	
CAV./PAD SIZE: 71x102	PKG. DESIGN			BOND DIAGRAM #: 05-9000-0580	REV: A



POWER DISSIPATION = 50mW max.

5V TYP. EXPECTED CURRENT: 530uA 5V MAX. EXPECTED CURRENT: 1mA
 40V TYP. EXPECTED CURRENT: 200nA 40V MAX. EXPECTED CURRENT: 2uA

8 pin Thin QFN Package

PN19 BURNIN

FOR MAX1553 AND MAX1554